

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

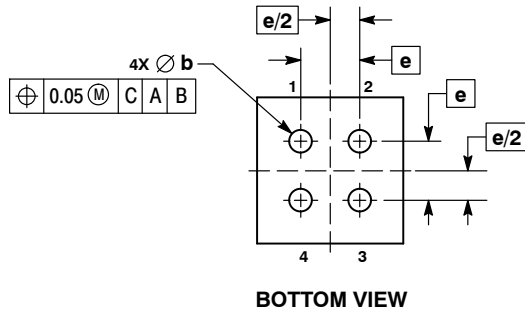
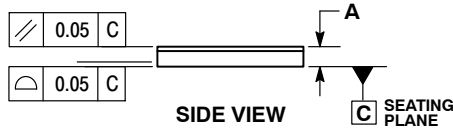
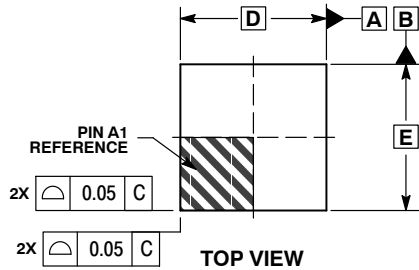
ON Semiconductor®



SCALE 4:1

**XFLGA4 1.61x1.61**  
**CASE 614AB**  
**ISSUE O**

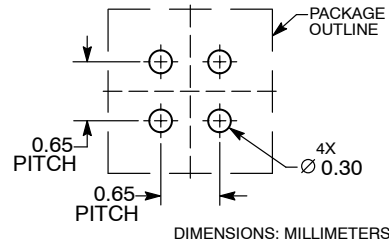
DATE 16 APR 2013



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.20	0.24
b	0.27	0.33
D	1.61	BSC
E	1.61	BSC
e	0.65	BSC

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>XFLGA4 1.61X1.61</b>	<b>PAGE 1 OF 1</b>

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